



SOT1158-1

DFN2512-12: plastic thermal enhanced extremely thin small outline package; no leads; 12 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2512-12
Package type industry code	DFN2512-12
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	17-12-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	1.1	-	1.2	1.3	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	

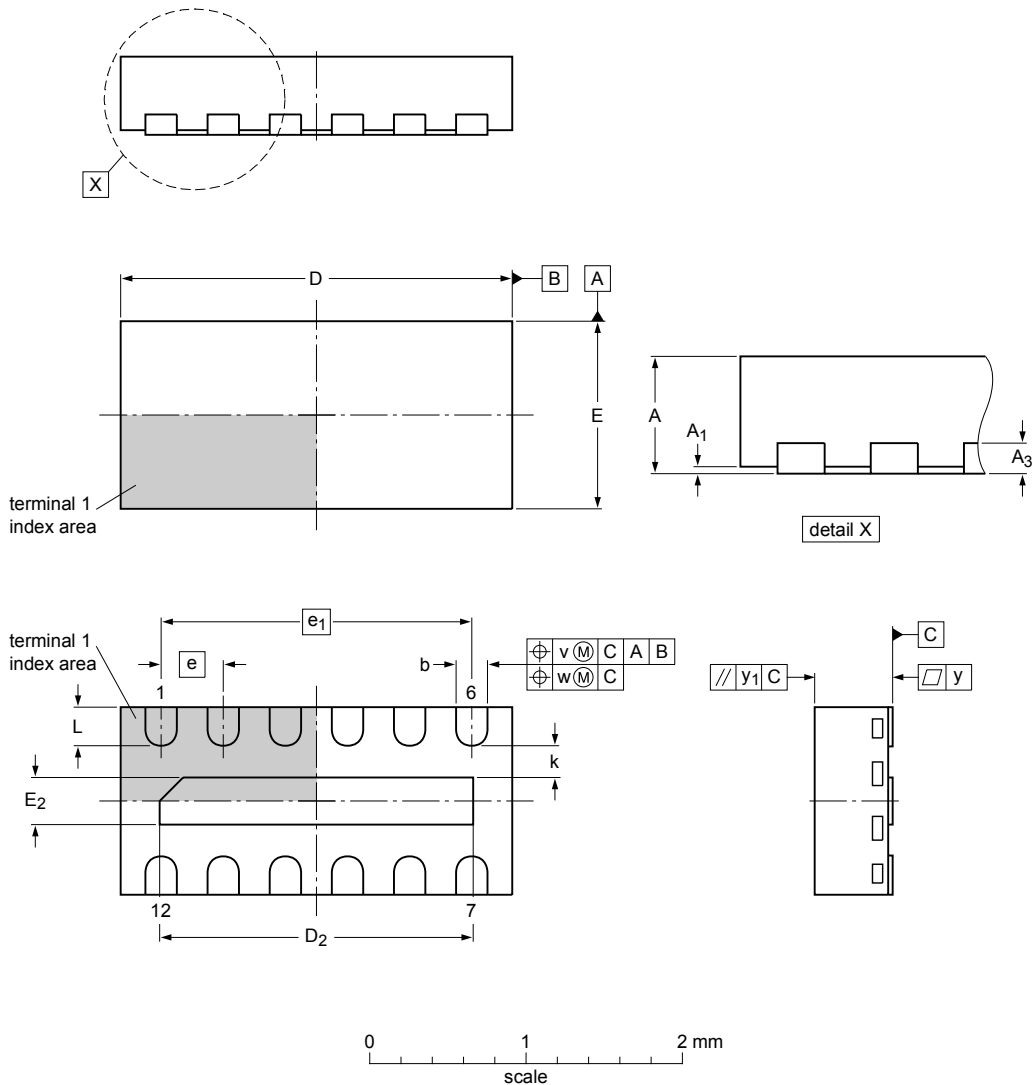


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2. Package outline

HXSON12: plastic thermal enhanced extremely thin small outline package; no leads; 12 terminals; body 1.2 x 2.5 x 0.5 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	D ₂	E	E ₂	e	e ₁	k	L	v	w	y	y ₁
max	0.5	0.05		0.25	2.6	2.1	1.3	0.35				0.30				
mm nom			0.127	0.20	2.5	2.0	1.2	0.30	0.4	2	0.2	0.25	0.1	0.05	0.05	0.05
min		0.00		0.15	2.4	1.9	1.1	0.25				0.20				

Note

1. Plastic or metal protrusions of 0.075 maximum per side are not included.

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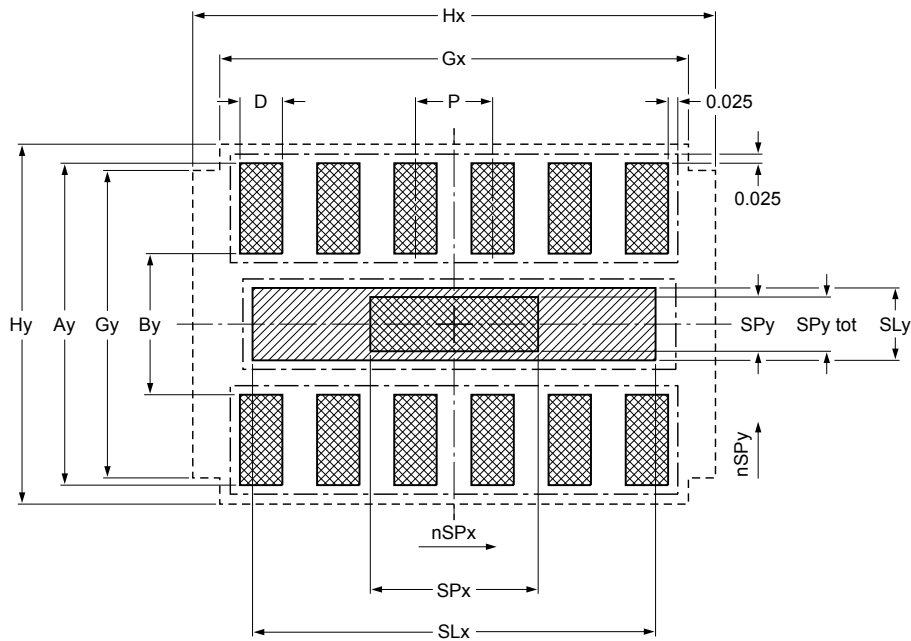
Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1158-1	---	---	---		09-12-16 09-12-17

Fig. 1. Package outline DFN2512-12 (SOT1158-1)

3. Soldering

Footprint information for reflow soldering of HXSON12 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist

DIMENSIONS in mm

P	Ay	By	D	SLx	SLy	SPx	SPy	Gx	Gy	Hx	Hy
0.40	1.75	0.75	0.22	2.1	0.35	0.9	0.2	2.45	1.45	2.75	2.0

Issue date ~~11-06-27~~
11-07-06

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Fig. 2. Reflow soldering footprint for DFN2512-12 (SOT1158-1)

4. Legal information

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Date of release: 8 February 2016
